



**POLYRACK
TECH-GROUP**
Steinbeisstraße 4
75334 Straubenhardt
Deutschland
Tel. +49 (0)7082 7919-0
info@polyrack.com
www.polyrack.com

Press release

POLYRACK at SPS 2019: Case and System applications for individual requirements

Hall 3C, Booth 531

Straubenhardt (Germany), October 2, 2019 – The POLYRACK TECH-GROUP will be presenting their wide range of case and system solutions from November 26th to 28th 2019 at SPS in Nuremberg (Hall 3C, Booth 531). Customer-specific system applications from various branches and application fields including integration of electronics and a range of HMI and MMI applications will be displayed.

For the control and drive technology, particularly for industrial environments, POLYRACK presents its **PanelIPC 2-series**. These Panel-PC-solutions comply with the protection class IP54 and are available in sizes from 10.1" to 21.5" as well as in different materials such as milled aluminium or sheet metal bending solutions. Resistive single-touch or multi-touch capable touchscreens (PCAP) in different glass thicknesses are options for the user interface. For example operating concepts with gesture control may be projected for smart production operating as well. Customer specific printing and anti-fingerprint coating are available on request. In order to use the advantages of different materials, other technologies are available for customers to realize individual requirements in materials, such as plastics and cast components – also in a material combination.

Small Form Factor with EmbedTEC: The aluminium desktop case is the elegant design for small form factors such as embedded NUC (eNUC), pico-ITX (pITX, 2.5"), SMARC, QSeven and SBCs as well as the Raspberry Pi. It comes with a changeable front I/OShield as well

as a massive aluminium cover for the heat dissipation. The cover might as well be replaced by a heat sink for improved performance. Alternatively, perforated side panels or small fans can add to the cooling performance on top. POLYRACK also offers various adaptations and mounting options for applications in the fields of automatization and IoT.

Supporting enclosure series like **SmarTEC** for high quality systems such as passive cooled Mini-PCs, **EmbedTEC** for Embedded Computing and HMI-applications as well as **Backplanes** for the high-speed domain based on VPX and CompactPCI serial standards are complementary to the product portfolio of the electronic packaging specialist POLYRACK. All solutions are characterized by matching interaction of mechanics, plastics, electronics and surface finish – fine-tuned to the target market.

Pictures:



Picture 1: The PanelPC 2-Series is available in different display sizes and user interfaces.



Picture 2: EmbedTEC for Small Form Factor (SFF)

###

About POLYRACK TECH-GROUP (www.polyrack.com)

The POLYRACK TECH-GROUP develops and manufactures high quality standard cases and customer-specific enclosure solutions. Thanks to a broad range of technologies in the mechanical manufacturing, systems engineering / electronics, plastics and surface finishing, POLYRACK offers electronic packaging for every need. The service offering extends from consulting in the conception phase, development, manufacturing and assembly right through to logistic solutions and sourcing services.

POLYRACK Electronic-Aufbausysteme GmbH (Electronic Packaging and Systems Technology), RAPP Kunststofftechnik GmbH (Plastics Technology), RAPP Oberflächenbearbeitung GmbH (Surface Treatment) and subsidiaries in Switzerland, Belgium, America and China. The owner-managed company has approx. 450 employees worldwide and achieved a turnover of 68.7 million euros in the group in fiscal year 2018.

Press contact:

POLYRACK TECH-GROUP, Maximilian Schober,
Tel: +49 7082 7919-771, e-Mail: maximilian.schober@polyrack.com

Agentur Lorenzoni GmbH, Public Relations, www.lorenzoni.de
Christine Schulze, Tel: +49 8122 55917-14,
e-Mail: christine@lorenzoni.de